

DESCRIPTION

The fundamental of SP6018 synchronous rectifier (SR) driver IC is based on our U.S. patented methods that utilize the principle of "prediction" logic circuit. The IC deliberatesprevious cycle timing to control the SR in present cycle by "predictive" algorithm that makes adjustments to the turn-off time, in order to achieve maximum efficiency and cross-conduction at the same time. Specially, SP6018 is designed for Resonance. It also maintains the MOSFET's body diode conduction at minimum level. The SP6018 is capable to adapt in almost all existing adaptors with few adjustments considered necessary.

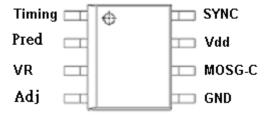
APPLICATIONS

- Servers & workstations
- Storage area network power supplies
- Telecommunication converters
- Embedded systems
- Industrial & commercial systems using high current processors

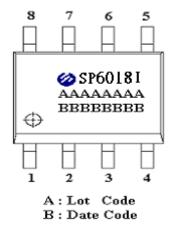
FEATURES

- Offers efficiency improvement over Schottky Diode (depends on drive configuration of the SR).
- Drives all Power MOSFET.
- Prediction gate timing control.
- Minimum MOSFET body diode conduction.
- Operating frequency up to 400 KHz.
- Synchronize to transformer secondary voltage waveform.

PIN CONFIGURATION (SOP-8)

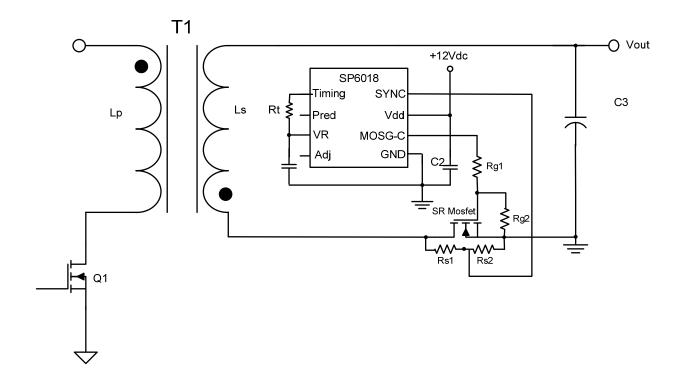


PART MARKING



www.DataSheet4U.com

TYPICAL APPLCATION CIRCUIT



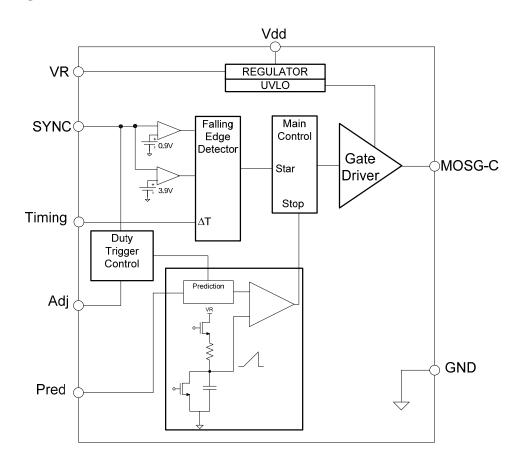
PIN DESCRIPTION

Pin	Symbol	Description	
1	Timing	Discontinuous current filter timing adjustment resistor connection.	
2	Pred	Capacitor to store previous cycle timing for SR MOSFET.	
3	VR	oltage Regulator.	
4	Adj	Trigger point adjustment for Dynamic state.	
5	GND	Ground connection.	
6	MOSG-C	Catch MOSFET gate drive.	
7	Vdd	DC supply voltage.	
8	SYNC	Synchronized signal from the V _{DS} of SR MOSFET.	

www.DataSheet4U.com



BLOCK DIAGRAM



ORDERING INFORMATION

Part Number	Package	Part Marking		
SP6018S8RGB	SOP-8	SP6018 I		
SP6018S8TGB	SOP-8	SP6018 I		

※ SP6018S8RGB: 7" Tape Reel; Pb − Free; Halgon − Free

※ SP6018S8TGB: Tube; Pb − Free; Halgon − Free

ABSOULTE MAXIMUM RATINGS (TA=25°C, unless otherwise specified.)

The following ratings designate persistent limits beyond which damage to the device may occur.

	Symbol	Parameter	Value	Unit
	V_{dd}	DC Supply Voltage	16	V
	I_{OUT}	Peak Source Current (Pulsed)	1	A
		Peak Sink Current (Pulsed)	1	A
WW	w.DatpSheet4	Power Dissipation @ $T_A=85^{\circ}C$ (*)	0.25	W
	$T_{\rm J}$	Operating Junction Temperature Range	-40 to125	$^{\circ}\!\mathbb{C}$
	T_{STG}	Storage Temperature Range	-40 to 150	$^{\circ}\!\mathbb{C}$
	T_{LEAD}	Lead Soldering Temperature for 5 sec.	260	$^{\circ}\!\mathbb{C}$

THERMAL RESISTANCE

Symbol	Parameter	Value	Unit
Rөjc	Thermal Resistance Junction – Case (*)	45	°C/W

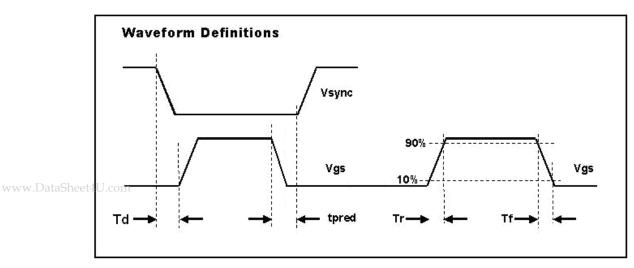
^(*) The power dissipation and thermal resistance are evaluated under copper board mounted with free air conditions.

ELECTRICAL CHARACTERISTICS

(T_A=25°C, V_{dd}=12V, Freq. =300 KHz, Duty Cycle=50%, unless otherwise specified.)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
SUPPLY INI	PUT					
Inn	Cumply augment	No load		4	7	mA
Idd	Supply current	V _{SYNC} =0V, No load		5	8	mA
Vdd	Supply voltage	Idd _{peak} < 2A			16	V
Vdd on	Enable voltage		9.0	10.0	11.0	V
SYNC REFE	ERENCE (SYNC)		·			
Vshth	SYNC high threshold			3.9		V
Vslth	SYNC low threshold			0.9		V
Vsync	SYNC clamp voltage	Isync=3mA		5		V
Isync	SYNC input current				3	mA
Voltage Regu	llator REFERENCE (VR)					
Ivr	VR Output Current				20	mA
ON TIME D	UTY SETUP (PIN 6)		·			
Ton-time				20		us
MOSFET GA	ATE DRIVER (MOSG-C)		·			
Voh	Output high voltage	Io = -200mA	10.5	11		V
Vol	Output low voltage	Io = 200mA		0.5	0.8	V
Td	Propagation delay	No load	50	80		ns
Tpred		No load		120		ns
Tr	Rise time	No load		10	25	ns
Tf	Fall time	No load		10	25	ns
Dynamic Pro	otect			•	•	•
Dt	Dynamic variable	Pin 4 open		600		ns
Ton-min	MOSG-C on time	PWM adjusts time > Dt		1		us

^(*) Tr & Tf are measured among 10% and 90% of starting and final voltage.



PERFORMANCE CHARACTERISTICS (T_A=25°C, unless otherwise specified.)

Figure 1: Supply Current vs Supply Voltage

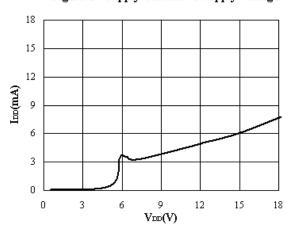
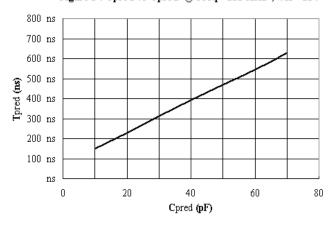
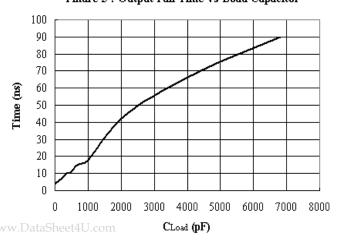


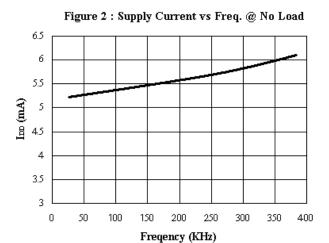
Figure 3 : Tpred vs Cpred @ Freq =100 KHz ; V_{1D} =10V



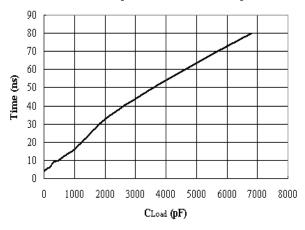
Fihure 5: Output Fall Time vs Load Capacitor



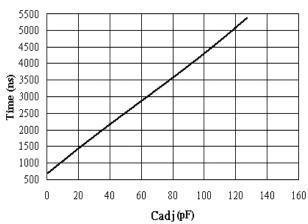
*Fig. 1 : No Load ; No SYNC *Fig. 4~5 : Frequency = 100 kHz.



Fihure 4: Output Rise Time vs Load Capacitor

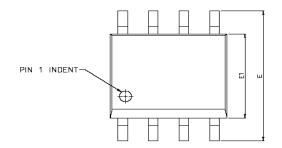


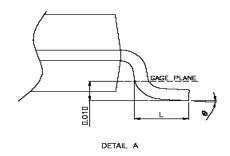
Fihure 6: Dynamic time vs Load Capacitor

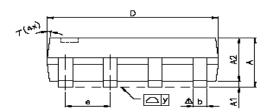


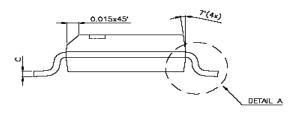


SOP- 8 PACKAGE OUTLINE









CVALDOLIC	DIMENSIONS IN MILLIMETERS		DIMENSIONS IN INCHES			
SYMBOLS	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.47	1.60	1.73	0.058	0.063	0.068
A1	0.10		0.25	0.004		0.010
A2		1.45			0.057	
Ь	0.33	0.41	0.51	0.013	0.016	0.020
С	0.19	0.20	0.25	0.0075	0.008	0.0098
D	4.80	4.85	4.95	0.189	0.191	0.195
Е	5.80	6.00	6.20	0.228	0.236	0.244
E1	3.80	3.90	4.00	0.150	0.154	0.157
е		1.27			0.050	
L	0.38	0.71	1.27	0.015	0.028	0.050
<u>∕</u> 2 y			0.076			0.003
0	0,		8*	0,		8*

www.DataSheet4U.com